

SANYO Semiconductors DATA SHEET

An ON Semiconductor Company

2SA1705 — PNP Epitaxial Planar Silicon Transistor

Low-Frequency Power Amplifier Applications

Applicaitons

· Voltage regulators, relay drivers, lamp drivers

Features

- · Adoption of FBET process
- · Fast switching speed

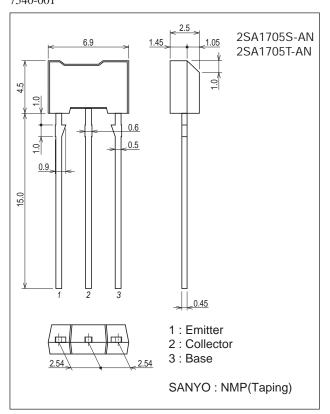
Specifications

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Collector-to-Base Voltage	VCBO		-60	V
Collector-to-Emitter Voltage	VCEO		-50	V
Emitter-to-Base Voltage	VEBO		-5	V
Collector Current	IC		-1	Α
Collector Current (Pulse)	ICP		-2	Α
Collector Dissipation	PC		0.9	W
Junction Temperature	Tj		150	°C
Storage Temperature	Tstg		-55 to +150	°C

Package Dimensions

unit : mm (typ) 7540-001

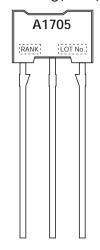


Product & Package Information

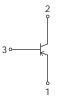
Package : NMP(Taping)JEITA, JEDEC : SC-71

• Minimum Packing Quantity : 2,500 pcs./box

Marking(NMP(Taping))



Electrical Connection



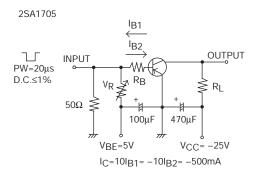
Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
Parameter	Syllibol	Conditions	min	typ	max	Offic
Collector Cutoff Current	ICBO	V _{CB} =-50V, I _E =0A			-100	nA
Emitter Cutoff Current	IEBO	V _{EB} =-4V, I _C =0A			-100	nA
DC Current Gain	h _{FE} 1	V _{CE} =-2V, I _C =-100mA	140*		400*	
DC Current Gain	h _{FE} 2	V _{CE} =-2V, I _C =-1A	30			
Gain-Bandwidth Product	fŢ	V _{CE} =-10V, I _C =-50mA		150		MHz
Collector-to-Emitter Saturation Voltage	V _{CE} (sat)	I _C =-500mA, I _B =-50mA		-180	-500	mV
Base-to-Emitter Saturation Voltage	V _{BE} (sat)	I _C =-500mA, I _B =-50mA		-0.9	-1.2	V
Output Capacitance	Cob	V _{CB} =-10V, f=1MHz		12		pF
Collector-to-Base Breakdown Voltage	V(BR)CBO	IC=-10μA, IE=0A	-60			V
Collector-to-Emitter Breakdown Voltage	V(BR)CEO	IC=-1mA, RBE=∞	-50			V
Emitter-to-Base Breakdown Voltage	V(BR)EBO	I _E =-10μA, I _C =0A	-5			V
Turn-ON Time	ton			40		ns
Storage Time	tstg	See specified Test Circuit.		300		ns
Fall Time	tf			30		ns

*: The 2SA1705 is classified by 100mA hFE as follows:

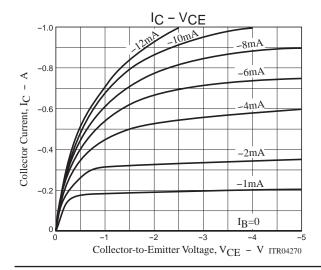
Rank	S	T
hFE	140 to 280	200 to 400

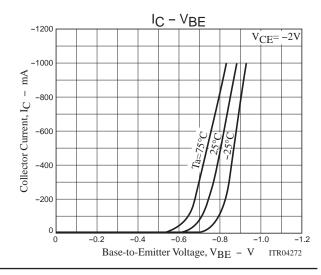
Switching Time Test Circuit

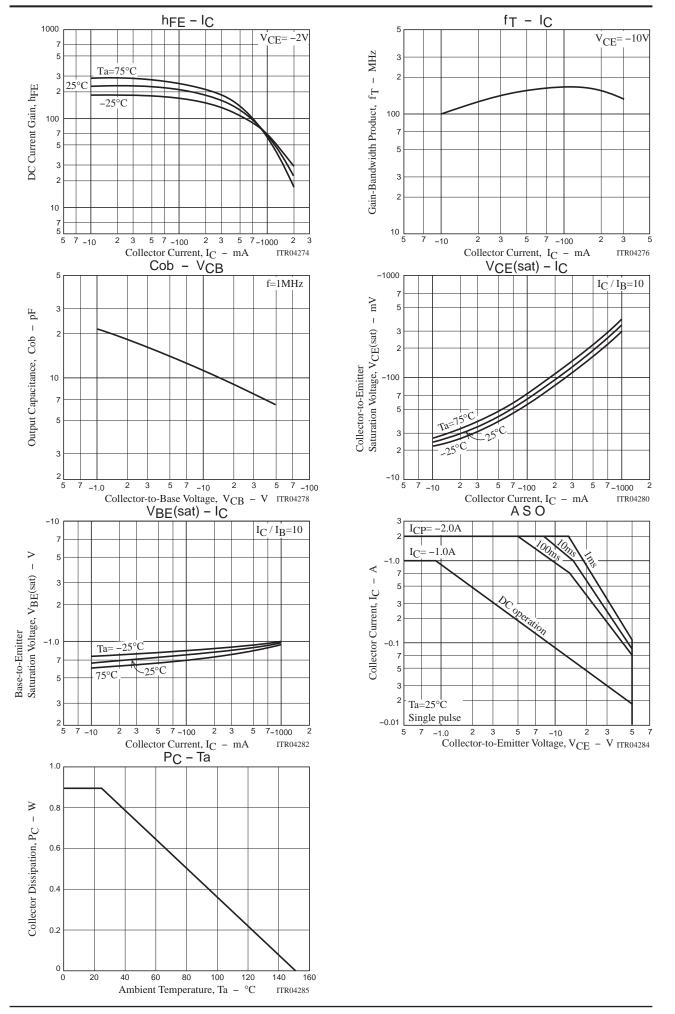


Ordering Information

Device	Package	Shipping	memo
2SA1705S-AN	NMP(Taping)	2,500pcs./box	Db Fron
2SA1705T-AN	NMP(Taping)	2,500pcs./box	Pb Free







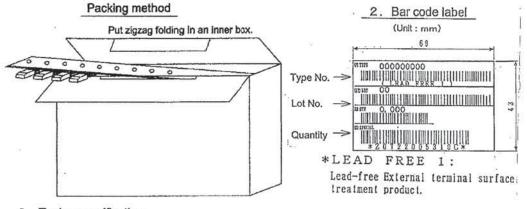
Bag Packing Specification

2SA1705S-AN, 2SA1705T-AN

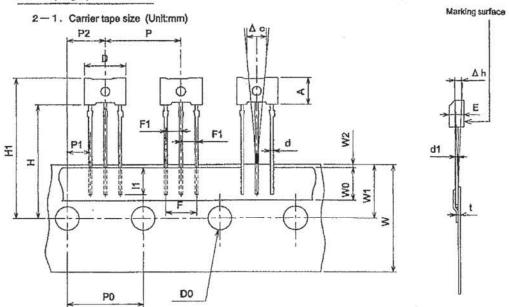
NMP (Zigzag folding)

Storage package	Package	Maximum Number of devices contained (pcs.)		Packing format		
Outline name type	Inner box No.	Storage quantity	Outer box (C-6)	Outer box (C-8)		
NMP	AN/AZ	C-3 Inner box Dimensions :rnm(external) 3 3 0 × 4 5 × 1 2 5	2,500	8 inner boxes contained(20,000pcs.) Outer box Dimensions:mm(external) 5 8 5 × 3 4 5 × 1 9 5	4 inner boxes contained (10,000pcs. Outer box Dimensions:mm(externa 3 4 5 × 3 0 0 × 1 9 5	

1. Packing format



2. Taping specifications

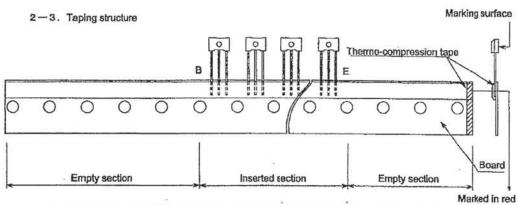


2-2. Taping size standard

Item	Symbol	Standard	Tolerance
	D	6.9	±0.2
Work piece outside diameter	E	2.5	±0.2
Work piece height	Α	4.5	±0.2
Lead wire diameter	d	0.5	±0.1
Lead wire thickness	d1	0.45	±0.1
Bonded lead wire	11	3.0MIN	
Pitch between products	Р	12.7	±0.5
Pitch between perforations	P0	12.7	±0.2
Total pitch for 21 perforations	P0×20	254.0	±1.0
Distance between lead wire	F	5.0	+0.8
Lead wire pitch distance	F1	2.54	+0.4
	P1	3.81	±0.3
Displacement of perforations	P2	6.35	±0.3
Displacement of tape	W2	0~0. 5	L

Unit:mm

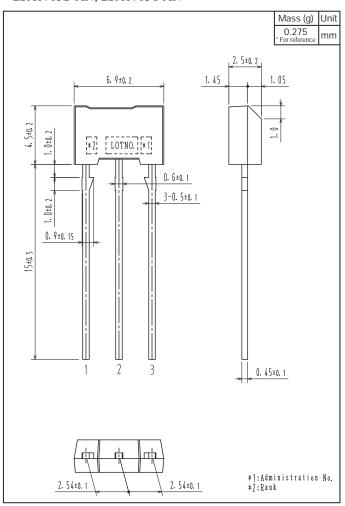
Item	Symbol	Standard	Tolerance
Tape width	W	18.0	±0.5
Adhesive tape	Wo	6.0	±0.5
Displacement of perforations	W1	9.0	±0.5
Work piece bottom surface position	Н	19.0	+1.0
Work piece upper limit position	H1	23.5	±1.0
Perforations diameter	D0	φ4.0	±0.2
Tape thickness (total thickness)	t	0.6	±0.2
Product inclination	Δс	0	±0.7
Product inclination	Δh	0	±1.0



- · Provide an empty section for about three to five pleces in leading and end portions of the tape.
- · Provide an empty section in the fold-back portion.
- · Provide marking in red to the E-side end of the board.

Outline Drawing

2SA1705S-AN, 2SA1705T-AN



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